APPROVAL SHEET

To：

Customer P/N：

UDE P/N： SBA0-ZZ-0001

Description： SFP28 2X1 Ass'y
Press-Fit
Without Lightpipe
Contact Area : 30μ" min. Gold
Packing With Tray
preliminary

RoHS

Spec No.	Update Date	Revision
SBA020001-00	2020/3/20	A

Approved	Checked	Prepared

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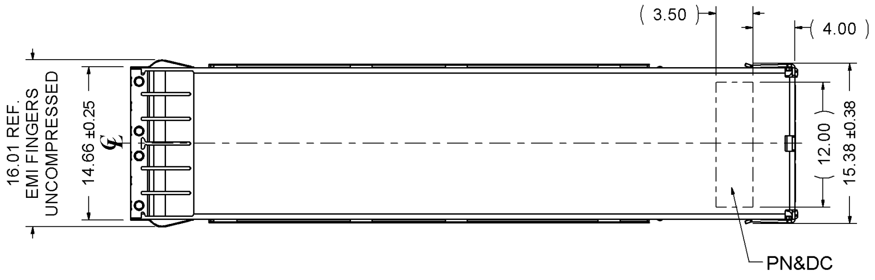
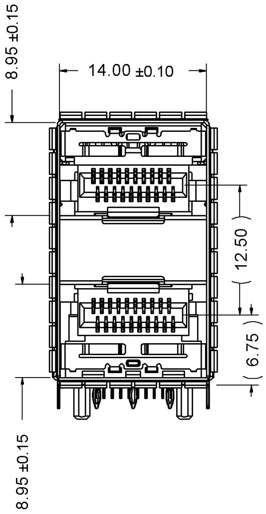
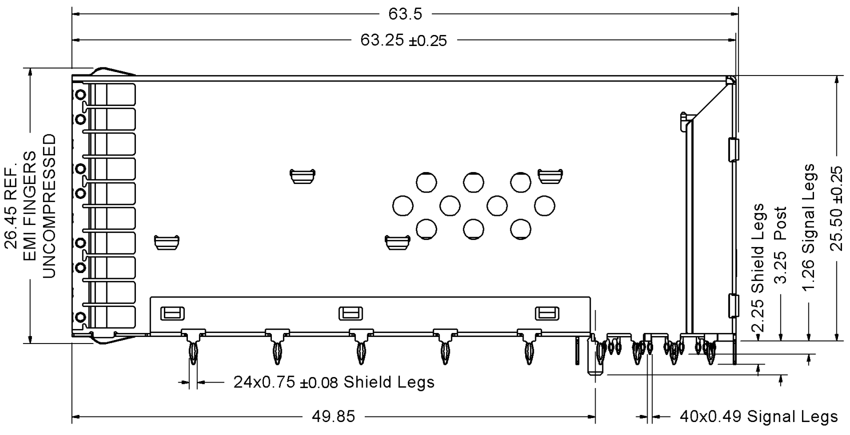
1. MECHANICAL DIMENSION

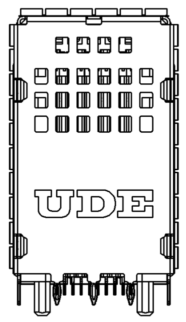
1.1 Product Dimension

Unit : mm	General Tolerance :	X.X : ± 0.38 X.XX : ± 0.20

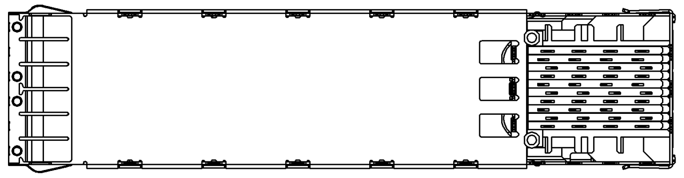








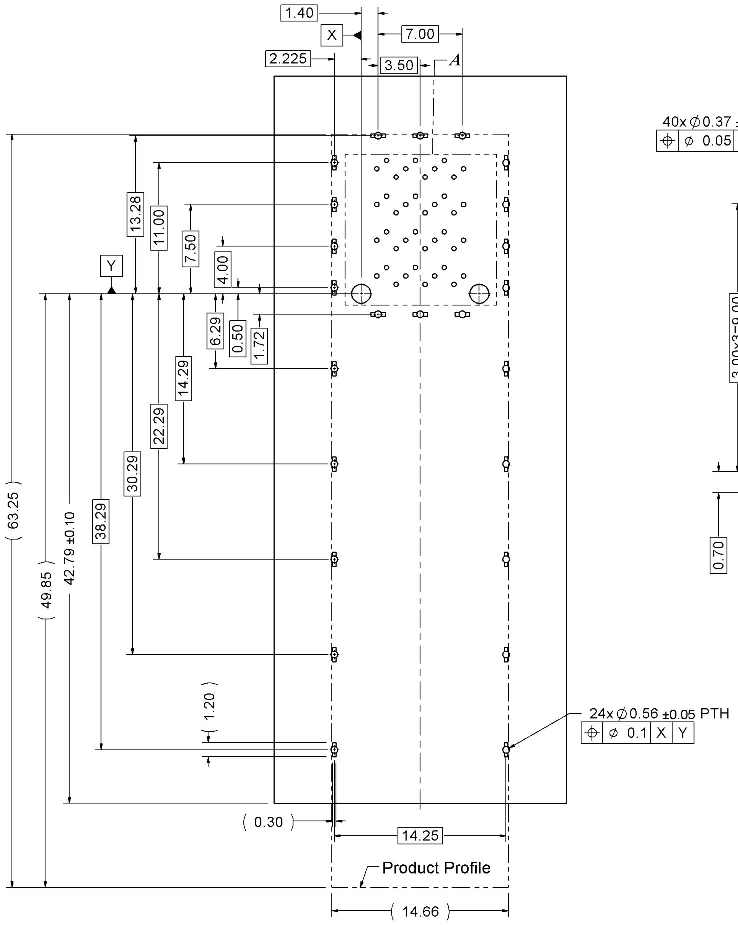
RIGHT VIEW

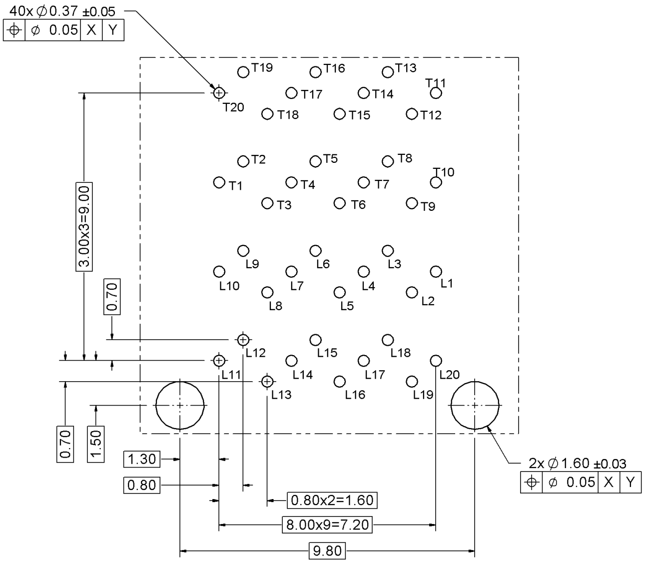


1.2 Recommened PCB Layout

Component Side of Board

All dimension tolerance are ±0.05mm unless otherwise specified





細部放大圖 A
比例 5 : 1

NOTES:

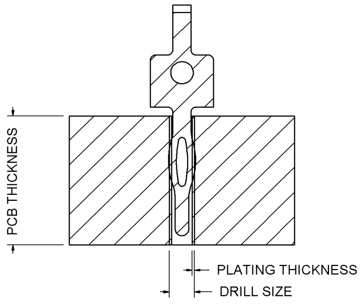
1.RECOMMENDED THRU HOLE PLATING INCLUDES

HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)

2.1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USB.

RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

PLATED THROUGH HOLE	0.56 SHIELD PINS	0.37 SIGNAL PINS
FINISHED HOLE DIAMETER	0.56 ±0.05	0.37 ±0.05
DRILLED HOLE DIAMETER	0.66	0.47
COPPER PLATING	0.025 min.	0.025 min.

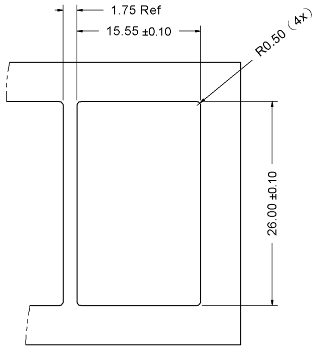


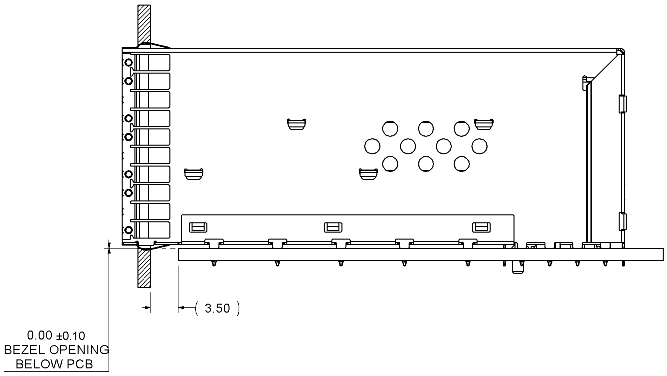
RECOMMENDED MOTHER BOARD
THROUGH HOLE DIMENSION

PRESS-FIT ASSEMBLIES
HAND PLACE USING PROPER SEATING FORCE TO ENGAGE ALL LEG TAILS INTO PLATED THRU-HOLES

ASSEMBLIES ARE TO BE SEATED PER THE INSTRUCTIONS ASSOCIATED WITH THE APPROPRIATE INSERTION TOOL
NOTE:UDE RECOMMENDS ONLY ONE CONNECTOR ASSEMBLY BE INSTALLED AT A TIME

1.3 Recommended Panel Cutout





1.4 Packing Information

24 pcs finished goods per tray

5 trays(120pcs finished goods) per master carton

2. REQUIREMENTS

2.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

2.2 Material

Top Shell : Copper Alloy,Thickness=0.25mm

Bottom Shell :Copper Alloy,Thickness=0.25mm

UD Mid Ground: Copper Alloy,Thickness=0.25mm

Inner Spring : SUS304, Thickness=0.20mm

EMI Spring Finger : Ph.Bronze, Thickness=0.08mm

Connector Housing: LCP. UL: 94V-0 Color:Black

Terminal: Copper Alloy,Thickness=0.20mm

2.3 Finish :

EMI Spring Finger：30u" min.Nickel overall

Terminal : 30u" min Gold Plating on contact area,30u" min.Nickel overall

2.4 Operating and Storage Temperature

Operating Temperature : -40°C to +85°C

Storage Temperature : -55℃ to +105℃

2.5 SFP+ specifications

Contact Current Rating: 0.5A (per contact)

Insulation Resistance : 1000MΩ min.

Dielectric Withstanding Voltage : 300VDC @1min.

Insertion force : 40N MAX.

Extraction force : 12.5N MAX.

Durability : 100 cycles MIN.

Cage Retention (Latch strength) : 90N Min.

2.6 Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

2.7 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

3. Revision History

Issue Date	Revision	Comments	Operator
2020/3/20	A	Initial Release .	Arjun